



Final Product/Process Change Notification

Document #:FPCN25758X

Issue Date:09 Aug 2024

Title of Change:	Assembly Material Change from 2.0mil Gold Wire to 2.0mil Palladium Coated Copper Wire for DFN 3x3 NCP59744 and NCP59748 Product at onsemi Seremban, Malaysia.Assembly Material Change from 2.0mil Gold Wire to 2.0mil Palladium Coated Copper Wire for DFN 3x3 NCP59744 and NCP59748 Product at onsemi Seremban, Malaysia.
Proposed First Ship date:	16 Nov 2024 or earlier if approved by customer
Contact Information:	Contact your local onsemi Sales Office or Andrew.Abarrientos@onsemi.com
PCN Samples Contact:	Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.
Additional Reliability Data:	Contact your local onsemi Sales Office or MohdAzizi.Azman@onsemi.com
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. onsemi will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com
Marking of Parts/ Traceability of Change:	Product traceability will be maintained by date code.
Change Category:	Assembly Change
Change Sub-Category(s):	Material Change

Sites Affected:

onsemi Sites

onsemi Seremban, Malaysia

External Foundry/Subcon Sites

None

Description and Purpose:

This final notification announces that onsemi has qualified a change in assembly material from 2.0mil gold wire to 2.0mil palladium-coated copper wire for the DFN 3x3 NCP59744 & NCP59748 product at onsemi Seremban, Malaysia.

	From	To
Bond Wire	2.0mil Gold Wire	2.0mil Palladium Coated Copper Wire

There is no product marking change as a result of this change.



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Reliability Data Summary:

QV DEVICE NAME: NCV59748MNADJTBG

RMS: 91784

PACKAGE: DFN10, 3x3, 0.5P

Test	Specification	Condition	Interval	Results
High Temperature Storage Life	JESD22-A103	Ta= 150 °C	1008 hrs	0/84
Preconditioning	J-STD-020 JESD-A113	MSL 1 @ 260 °C, Pre TC, uHAST, HAST for surface mount pkgs only		0/84
Temperature Cycling	JESD22-A104	Ta= -65°C to +150°C	500 cyc	0/84
Highly Accelerated Stress Test	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs	0/84
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/84
Resistance to Solder Heat	JESD22- B106	Ta = 265°C, 10 sec Required for through hole devices only		0/10
Solderability	JSTD002	Ta = 245°C, 5 sec		0/15
Physical Dimensions	JESD22-B120			

Electrical Characteristics Summary:

Electrical characteristics are not impacted.

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.

Part Number	Qualification Vehicle
NCP59744MN1ADJTBG	NCV59748MNADJTBG
NCP59748MN1ADJTBG	NCV59748MNADJTBG